PDMS Films for Printed Electronics – Methods and Advancements

February 15, 2018 Victoria Tran



DELPH®N



Device Protection Solutions

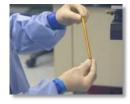


- Manufactures proprietary polymers and films
- Used to protect, process and transport fragile, high value devices



Specialty Printing



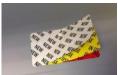


 Service provider that offers highly specialized printing capabilities



Cleanroom Tapes & Labels









 Manufactures specialty adhesives and elastomers for demanding cleanroom applications



Goal for FHE: Develop specialty substrates for flexible and stretchable electronics

Outline



- Properties & uses of silicones
- Characterizing challenges with silicones
- Overcoming challenges with silicones
- Continuing efforts in silicone films for printed, flexible and stretchable electronics

Silicone - Unique and Versatile

- Flexible
- Stretchable
- Easy to Process
- Good chemical resistance









Silicone in electronics

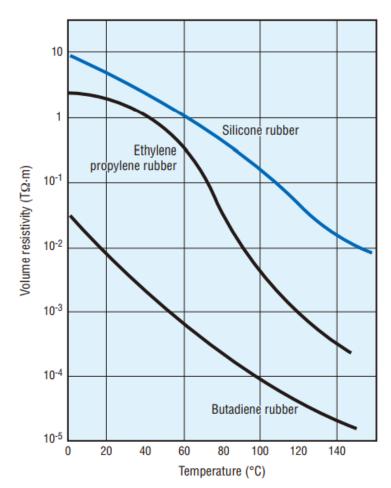


- Wide operating temperature range from -40 to +300°C
- Excellent electrical properties
 - Naturally insulative
 - Dope for conductivity
- UV resistance
- Vibration Absorbing

Resistance to humidity and

water

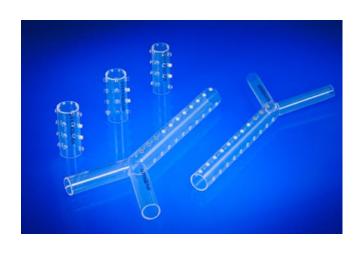


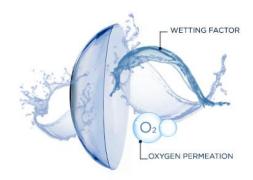




Silicone for Medical Devices

- Biocompatible
- Physiologically Inert











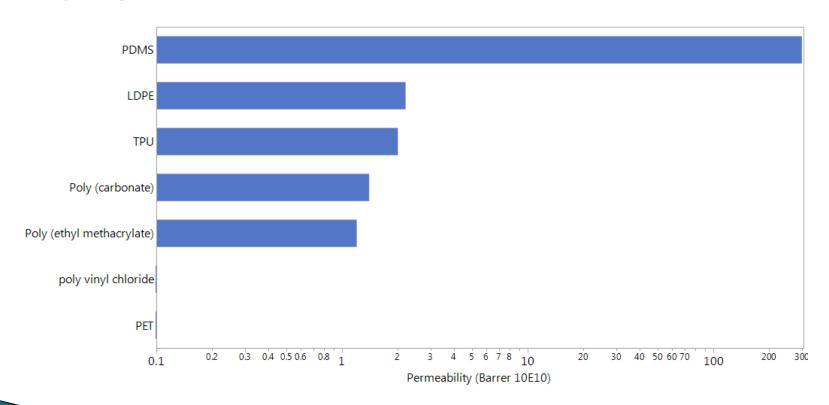




Oxygen Permeability

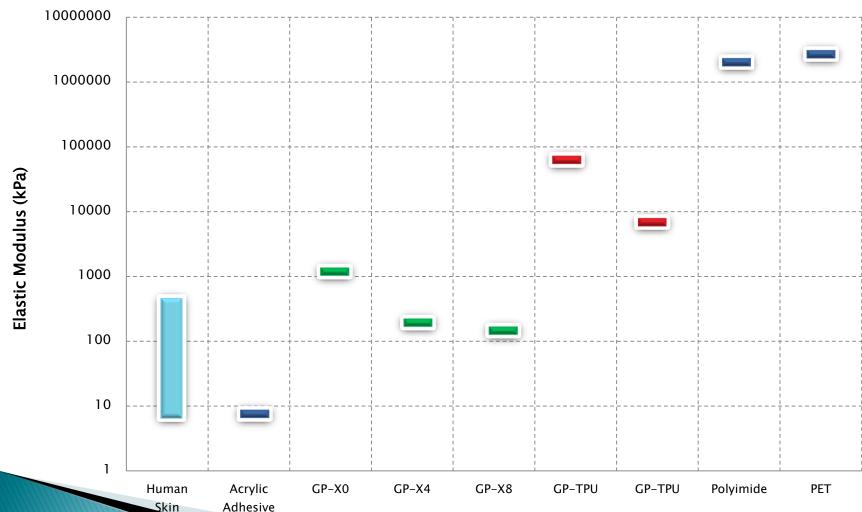


Silicone provides the necessary oxygen permeability for metabolic and biological processes



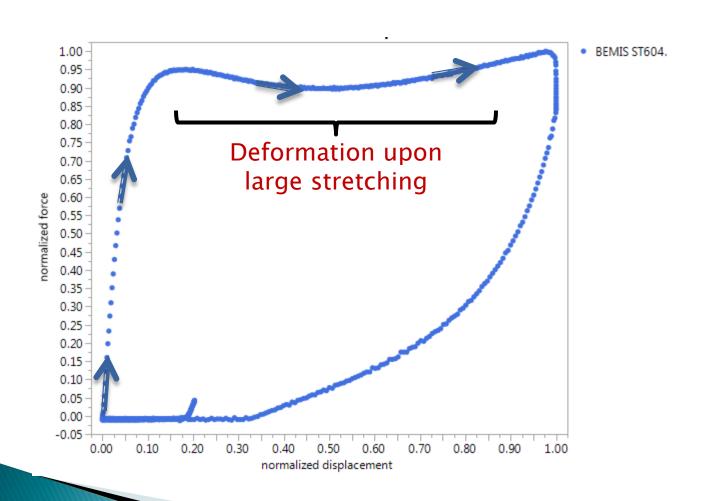
Silicone is Soft





TPUs & Elasticity

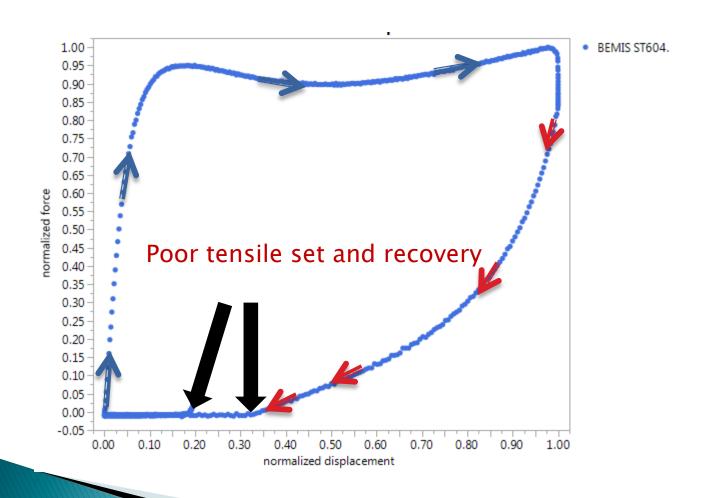






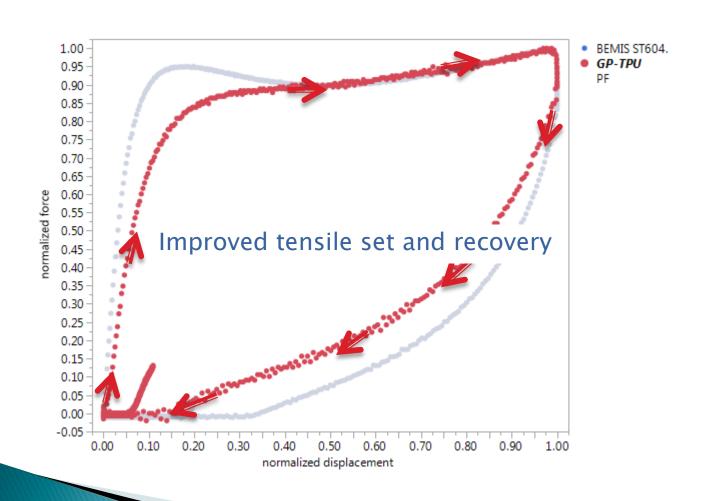
TPUs & Elasticity





FHE & Elasticity

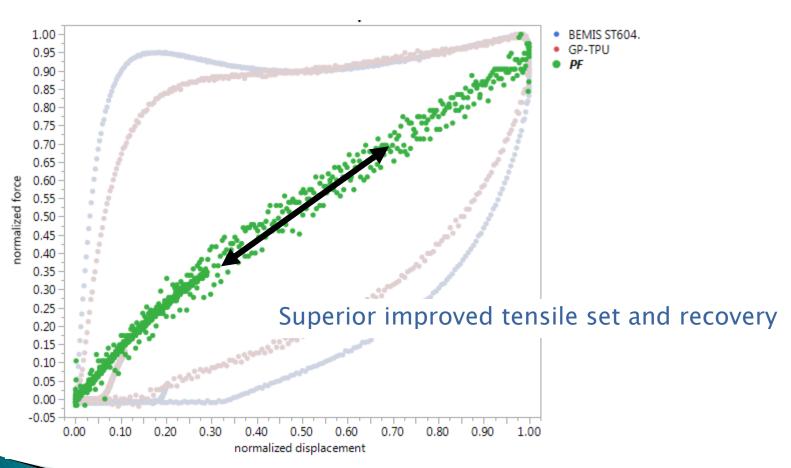






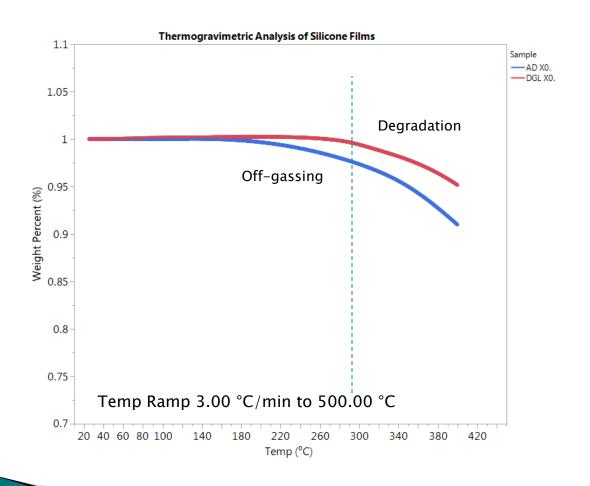
Silicones are Elastic





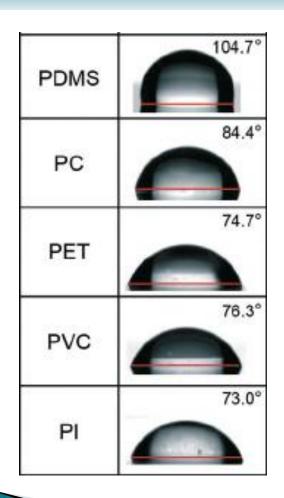
Silicones are Heat Resistant





Challenges with Silicone





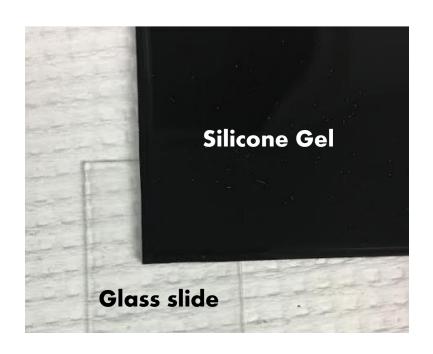
- Low Energy
- Low Energy Residue

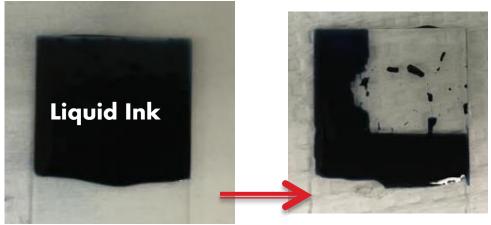


- Poor surface wetting
- Poor ink adhesion
- Poor device bonding

Silicone Residue Induces Dewetting



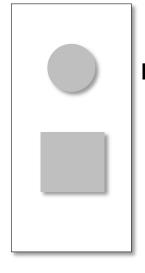




Ink dewets

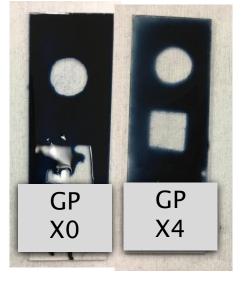
Ultra-Clean Silicone



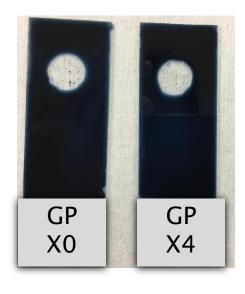


Positive control

Test sample



Standard Silicone

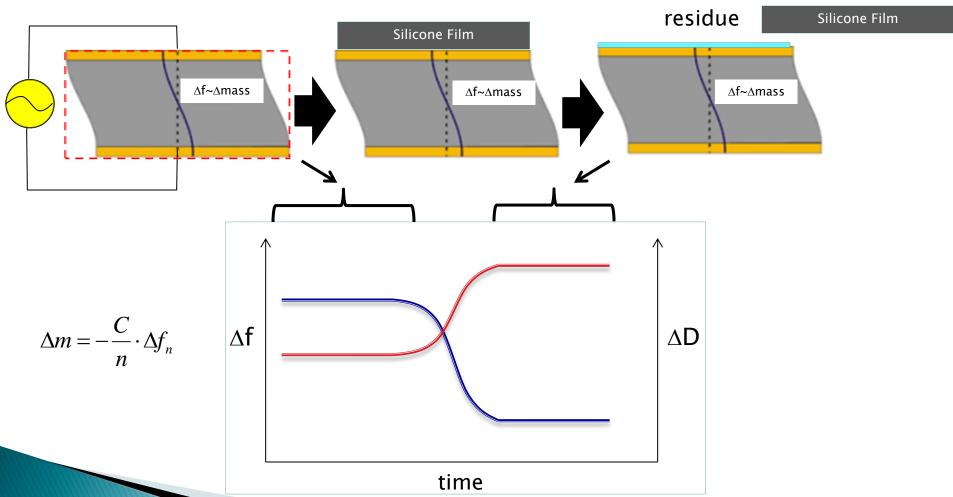


DGL film

- DGL film minimizes ink dewetting due to residue
- Can we quantify how much residue induces dewetting?

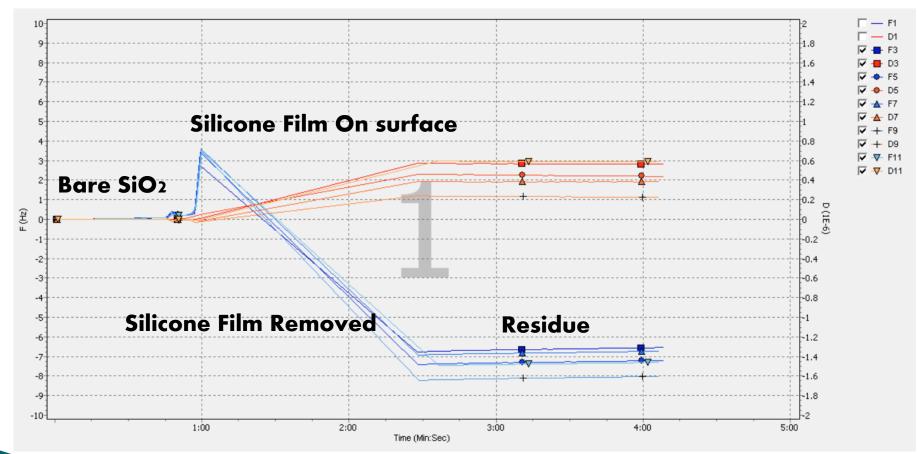
QCM for Residue Analysis





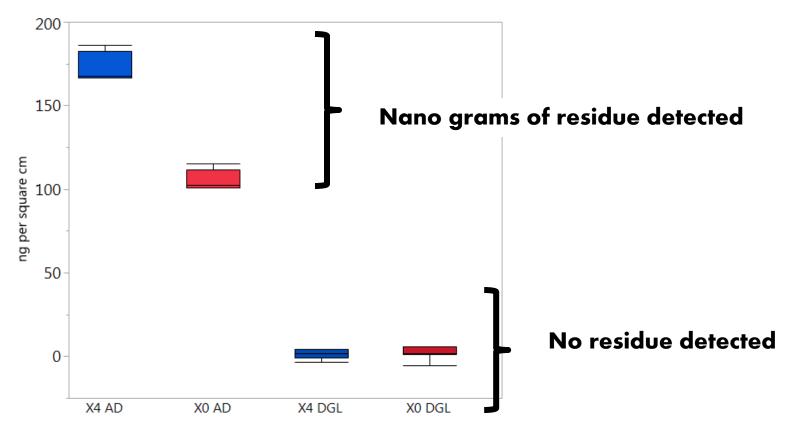
QCM for Residue Analysis





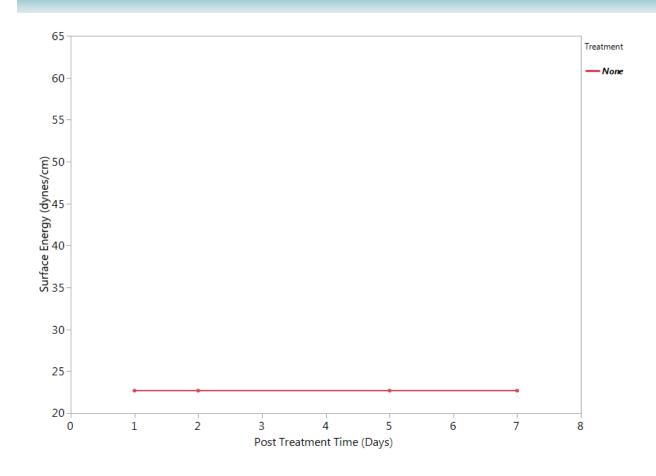
No Residue with DGL Films





Surface Energy - Silicone

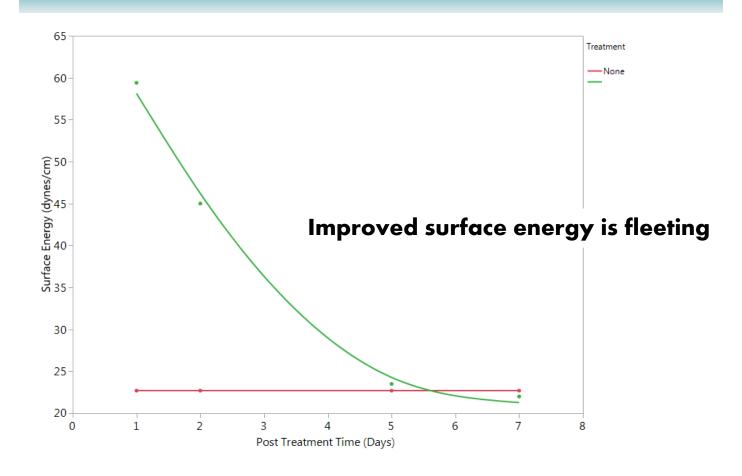






Oxygen Plasma Treatment

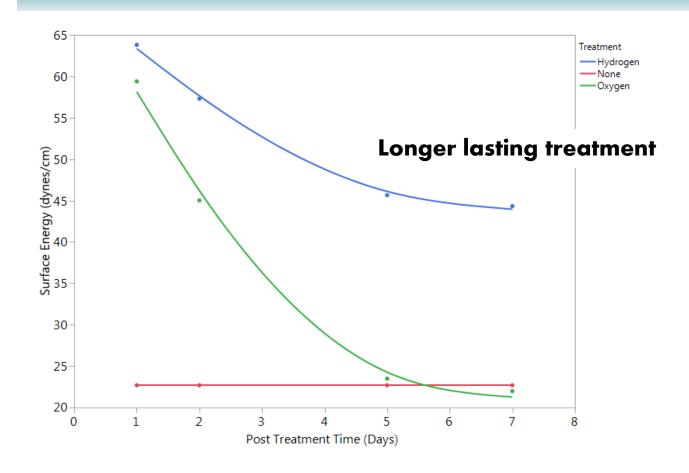






H₂ Plasma Treatment







Ink Adhesion



Post Stress Testing With Tape







No Ink Adhesion



Good Ink adhesion



Screen Printed

Ink Adhesion Summary



Treatment	Days of treatment Effectiveness	Ink Adhesion (EMS-Cl-1036)	Comments
UV Ozone	1	Good	Treatment <u>not</u> effective after ink cure
O ₂ Plasma	3	Good	Treatment <u>not</u> effective after ink cure
H ₂ Plasma	>7	Good	Treatment remains effective after ink cure

Continued Challenges



- Treatment Equipment and Time Availability
- Film handling
 - Soft
 - Film Support
 - Release Properties of film, coversheet and substrate
- Post printing proceses
- Goal: Work with partners interested in unique silicone and other substrates



Delphon Silicone Offerings

POLYCARBONATE COVERSHEET Silicone Film **POLYETHYLENE SUBSTRATE**

POLYETHYLENE COVERSHEET Silicone Film POLYESTER **SUBSTRATE**

POLYETHYLENE COVERSHEET Silicone Film **Bonding Agent POLYESTER SUBSTRATE**

Optional PSA

	DGL	PF	WF
Composition	Silicone	Silicone	Silicone
Appearance	Transparent	Transparent	Grey, Translucent
Silicone Thickness	1.5 mil, 6.5 mil, 17.0 mil	1.5 mil, 6.5 mil, 17.0 mil	1.5 mil, 6.5 mil, 17.0 mil
Coversheet	Polycarbonate, 5 mil	Polyethylene, 1 mil	Polyethylene, 1 mil
Substrate	Polyethylene, 4 mil	Polyester, 5 mil	Polyester, 5mil
Hardness (Shore A)*	32-50	32-50	32-50
Tensile Strength (MPa)*	6.7	6.7	6.7
Ultimate Elongation %*	>140	>140	140
Hysteresis**	<1%	<1%	<1%
Use Temperature	-40°C to 220°C	-40°C to 220°C	-40°C to +150°C
			Bonded to substrate. Available with optional pressure sensitive
Features	Ultraclean	Peelable	adhesive backing

Summary



- Silicone is a versatile substrate
 - Excellent biocompatibility, softness, and elasticity
- Learnings
 - Silicone residue and low energy potential problem for ink adhesion
 - Ultra-clean DGL can be a solution
 - Surface treatments have varying degrees of efficacy
- Continued challenges
 - Treatment availability and time
 - Film handling
- Goal: Work with partners to develop unique substrates for their products

Acknowledgements



- Joey Flores Automation specialist
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Thank you





